



**ALPHA & OMEGA**  
SEMICONDUCTOR

**AO3423**

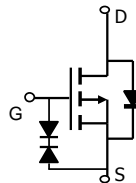
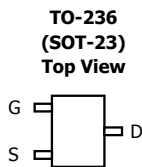
**P-Channel Enhancement Mode Field Effect Transistor**

**General Description**

The AO3423/L uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected. *AO3423 and AO3423L are electrically identical.*  
-RoHS Compliant  
-AO3423L is Halogen Free

**Features**

$V_{DS}$  (V) = -20V  
 $I_D$  = -2 A ( $V_{GS}$  = -10V)  
 $R_{DS(ON)} < 92m\Omega$  ( $V_{GS}$  = -10V)  
 $R_{DS(ON)} < 118m\Omega$  ( $V_{GS}$  = -4.5V)  
 $R_{DS(ON)} < 166m\Omega$  ( $V_{GS}$  = -2.5V)  
ESD Rating: 2000V HBM



**Absolute Maximum Ratings  $T_A=25^\circ\text{C}$  unless otherwise noted**

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>A</sup>	$T_A=25^\circ\text{C}$ <sup>F</sup>	-2	A
	$T_A=70^\circ\text{C}$ <sup>F</sup>	-2	
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	-8	
Power Dissipation <sup>A</sup>	$T_A=25^\circ\text{C}$	1.4	W
	$T_A=70^\circ\text{C}$	0.9	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$t \leq 10\text{s}$	65	90	$^\circ\text{C/W}$
	Steady-State	85	125	
Maximum Junction-to-Lead <sup>C</sup>	Steady-State	$R_{\theta JL}$	43	$^\circ\text{C/W}$

Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-0.5 -2.5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±10V			±1	μA
		V <sub>DS</sub> =0V, V <sub>GS</sub> =±12V			±10	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250μA	-0.7	-0.9	-1.4	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-5V	-8			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-2A T <sub>J</sub> =125°C		76 90	92 108	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A		94	118	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-1A		128	166	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-2A		6.8		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V	-0.6	-0.78	-0.95	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-1.8	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-10V, f=1MHz		512	620	pF
C <sub>oss</sub>	Output Capacitance			77		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			62		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		9.2	13	Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-10V, I <sub>D</sub> =-2A		5.5	6.6	nC
Q <sub>gs</sub>	Gate Source Charge			0.8		nC
Q <sub>gd</sub>	Gate Drain Charge			1.9		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-10V, R <sub>L</sub> =5Ω, R <sub>GEN</sub> =3Ω		5		ns
t <sub>r</sub>	Turn-On Rise Time			6.7		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			28		ns
t <sub>f</sub>	Turn-Off Fall Time			13.5		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =-2A, dI/dt=100A/μs		9.8	12	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =-2A, dI/dt=100A/μs		2.7		nC

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

D: The static characteristics in Figures 1 to 6,12,14 are obtained using <300 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C. The SOA curve provides a single pulse rating.

F: The maximum current rating is limited by bond-wires.

Rev 3 :May 2011

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

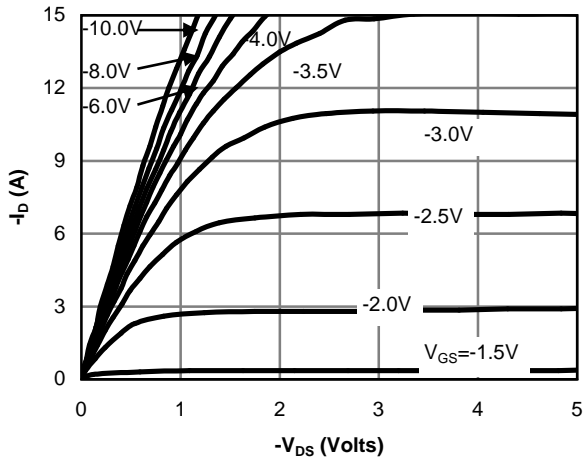


Fig 1: On-Region Characteristics

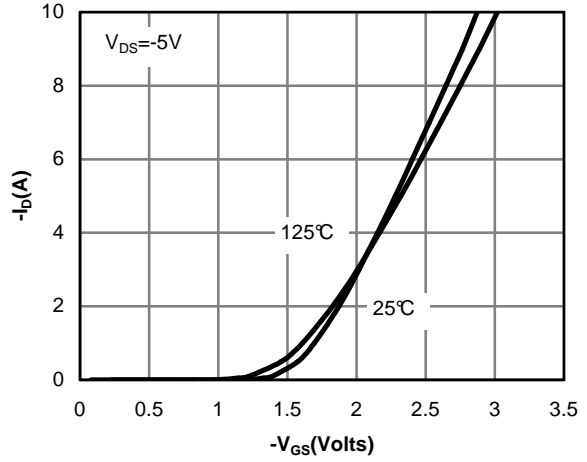


Figure 2: Transfer Characteristics

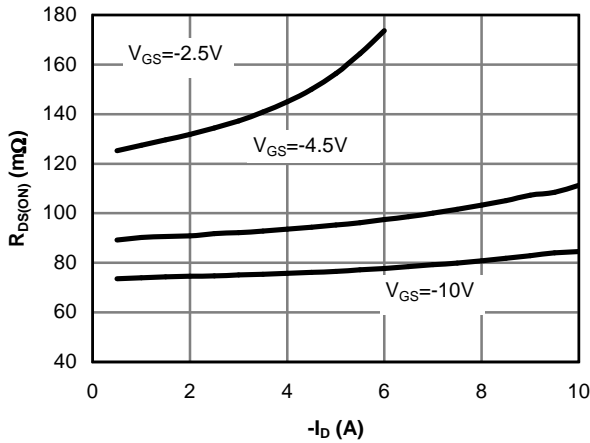


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

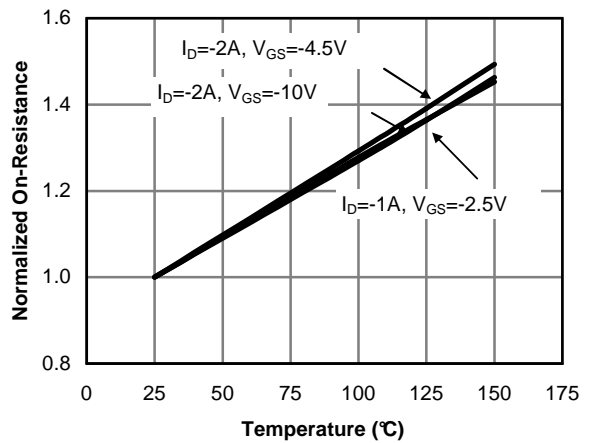


Figure 4: On-Resistance vs. Junction Temperature

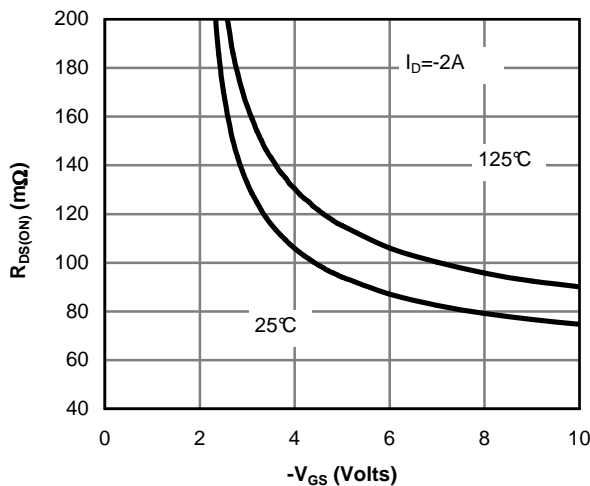


Figure 5: On-Resistance vs. Gate-Source Voltage

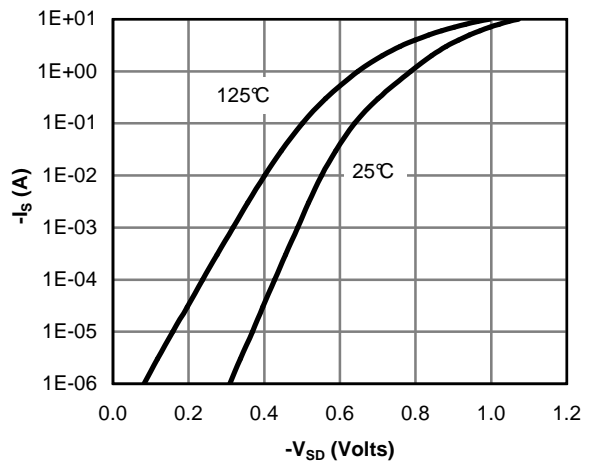


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

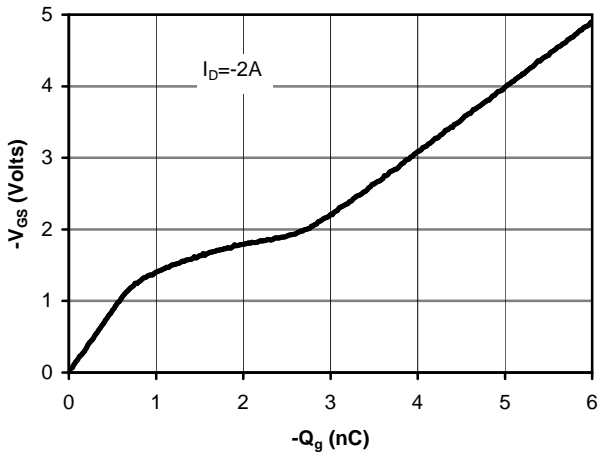


Figure 7: Gate-Charge Characteristics

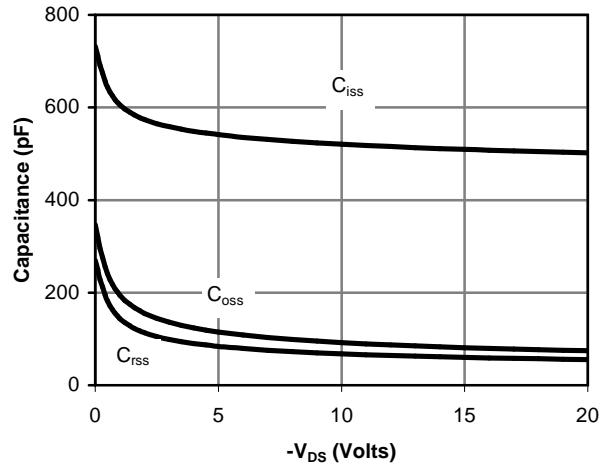


Figure 8: Capacitance Characteristics

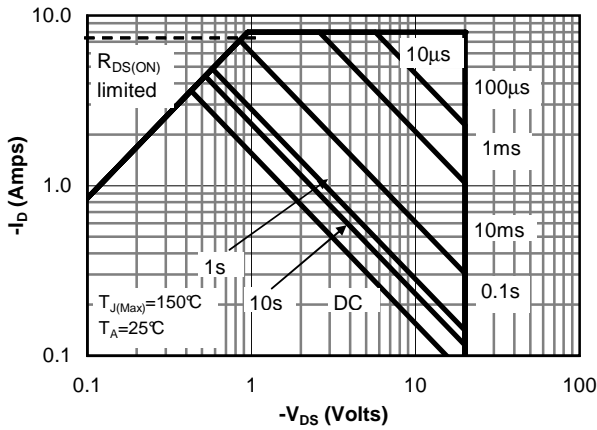


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

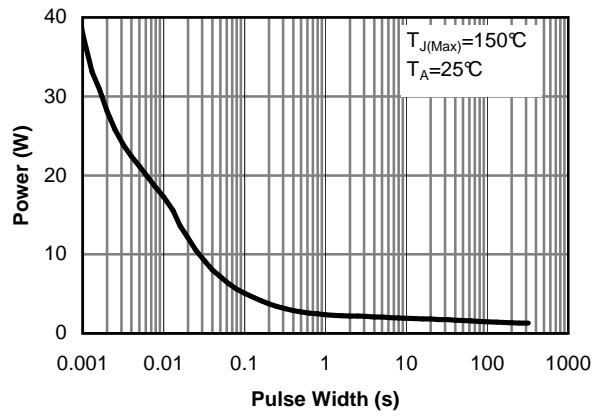


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

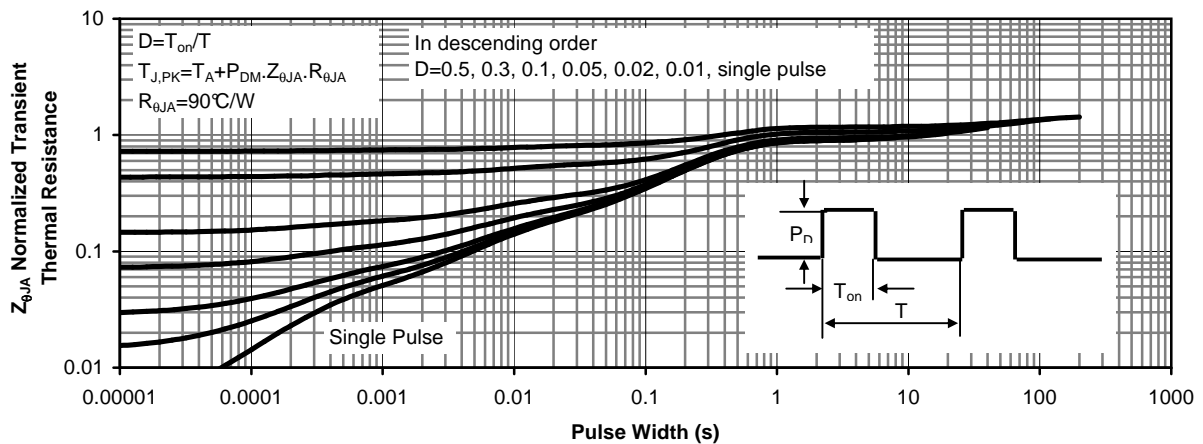


Figure 11: Normalized Maximum Transient Thermal Impedance